Dear Editor,

We would like to submit to your respectable journal our novel results on silicon etching

in the 25 wt % TMAH water solution. We developed a new etching technique using simulations and experiments which allows controllable arrangement of integrated obstacles in silicon microchannels. As the convex corner compensation is not necessary, obtained 3D silicon structures could be easily used for future designs of lab-on-chip platforms that contain parts based on obstacle mechanisms (like micromixers, DLD separators, cell peg). Authors claim that the submitted original scientific paper has not been published elsewhere and the paper has been written and approved by all the stated authors. The manuscript is currently not being considered for publication by any other journal and it will not be submitted for publication elsewhere while in the reviewing process in the journal Hemijska industrija.

Authors declare no conflict of interest.

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Sincerely,

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